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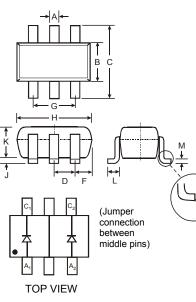
SURFACE MOUNT SCHOTTKY BARRIER DIODE ARR

Features

- Low Forward Voltage Drop •
- Fast Switching •
- Ultra-Small Surface Mount Package
- PN Junction Guard Ring for Transient and ESD Protection
- Lead Free/RoHS Compliant (Note 3)
- "Green" Device (Note 4 and 5)

Mechanical Data

- Case: SOT-363 •
- Case Material: Molded Plastic. UL Flammability • Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed . over Alloy 42 leadframe).
- Orientation: See Diagram
- Marking: KLC (See Page 3)
- Weight: 0.006 grams (approximate)



SOT-363									
Dim	Min	Max							
Α	0.10	0.30							
В	1.15 1.35								
С	2.00 2.20								
D	0.65 No	ominal							
F	0.30	0.40							
н	1.80	2.20							
J	_	0.40 2.20 0.10 1.00							
κ	0.90	1.00							
L	0.25	0.40							
Μ	0.10	0.25							
α	0°	8°							
All Dim	ensions	in mm							

Maximum Characteristics @TA = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit		
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _{RWM} V _R	30	V		
Forward Continuous Current	(Note 1)	I _F	200	mA		
Repetitive Peak Forward Current	(Note 1)	IFRM	300	mA		
Forward Surge Current (Note	1) @ t < 1.0s	I _{FSM}	600	mA		
Power Dissipation	(Note 1)	Pd	200	mW		
Thermal Resistance, Junction to Ambient Air	(Note 1)	$R_{ heta JA}$	625	°C/W		
Operating and Storage Temperature Range		T _i , T _{STG}	-65 to +125	°C		

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Symbol Min Typ Max Unit				Test Condition		
Reverse Breakdown Voltage	(Note 2)	V _{(BR)R}	30	_	_	V	I _R = 100μA	
Forward Voltage		VF	_	_	240 320 400 500 1000	mV	$I_F = 0.1mA$ $I_F = 1mA$ $I_F = 10mA$ $I_F = 30mA$ $I_F = 100mA$	
Reverse Leakage Current	(Note 2)	I _R		_	2.0	μA	V _R = 25V	
Total Capacitance		CT	_	_	10	pF	V _R = 1.0V, f = 1.0MHz	
Reverse Recovery Time		t _{rr}	_	_	5.0	ns	I_F = 10mA through I_R = 10mA to I_R = 1.0mA, R_L = 100 Ω	

1. Device mounted on FR-4 PC board with recommended pad layout, which can be found on our website at

http://www.diodes.com/datasheets/ap02001.pdf.

2. Short duration pulse test used to minimize self-heating effect.

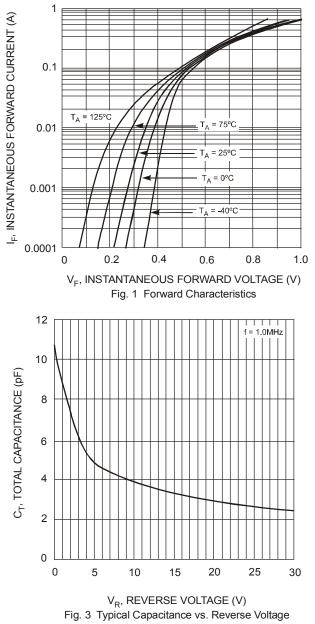
No purposefully added lead. 3.

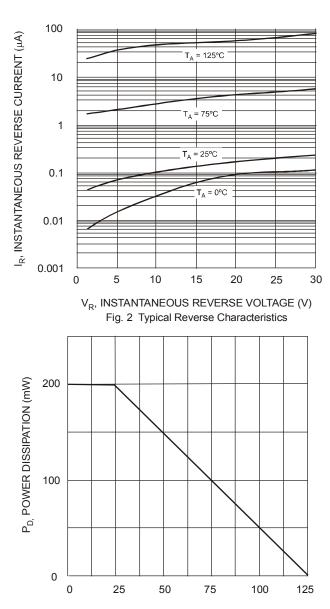
4.

Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date 5. Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

Notes:







T_A, AMBIENT TEMPERATURE (°C) Fig. 4 Power Derating Curve

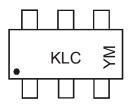


Ordering Information (Note 6)

Device	Packaging	Shipping
BAT54JW-7-F	SOT-363	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



KLC Product Type Marking Code YM = Date Code Marking Y = Year ex: N = 2002 M = Month ex: 9 = September

Date Code Key

Year	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	М	Ν	Р	R	S	Т	U	V	W	Х	Y	Z

Month	Jan	Feb	March	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	Ν	D

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